

CLAIMS

What is claimed is:

1. A method of cleaning a wafer, comprising the steps of:
 providing a surfactant composition solution;
 subjecting said wafer to a plurality of polishing steps;
 applying said surfactant composition solution to said wafer after at least one of said plurality of polishing steps;
 and
 rinsing said wafer.
2. The method of claim 1 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.
3. The method of claim 1 wherein said surfactant solution comprises an aqueous alcohol solution.
4. The method of claim 3 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

67,200-1192
2003-0312

5. The method of claim 1 wherein said rinsing said wafer comprises providing deionized water and rinsing said wafer using said deionized water.

6. The method of claim 5 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

7. The method of claim 5 wherein said surfactant solution comprises an aqueous alcohol solution.

8. The method of claim 3 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume.

9. The method of claim 8 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

67,200-1192
2003-0312

10. The method of claim 8 wherein said rinsing said wafer comprises providing deionized water and rinsing said wafer using said deionized water.

11. The method of claim 8 wherein said alcohol comprises octanol.

12. The method of claim 8 further comprising ethylene oxide in said aqueous alcohol solution.

13. A method of cleaning a wafer, comprising the steps of:
providing a surfactant composition solution;
subjecting said wafer to a plurality of polishing steps;
applying said surfactant composition solution to said wafer after each of said plurality of polishing steps; and
rinsing said wafer.

14. The method of claim 13 wherein said surfactant solution comprises an aqueous alcohol solution.

67,200-1192
2003-0312

15. The method of claim 14 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume.

16. The method of claim 15 further comprising ethylene oxide in said aqueous alcohol solution.

17. A composition solution for rendering a surface on a wafer hydrophilic to facilitate rinsing of the wafer with water, comprising:

an aqueous solution comprising less than about 1% alcohol.

18. The composition solution of claim 17 wherein said alcohol is an alcohol having the formula $C_nH_{2n-1}OH$, where n is any one of the integers 4-12.

19. The composition solution of claim 17 wherein said alcohol is octanol.

20. The composition solution of claim 17 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume and ethylene oxide.